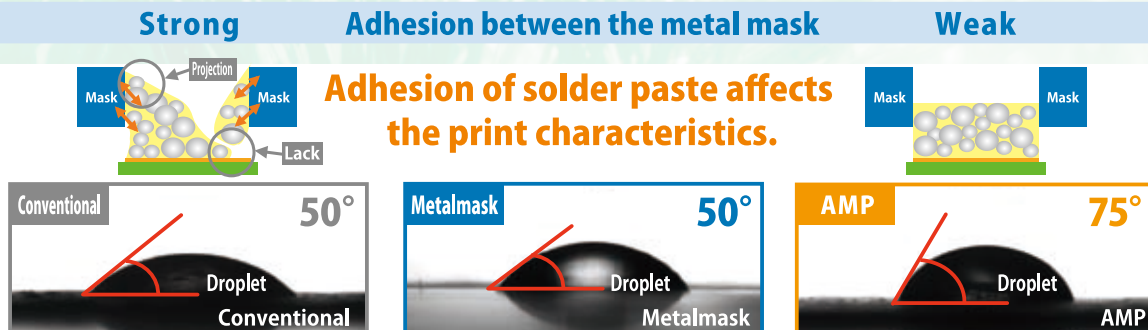


High Reliable Lead-free Solder Paste for Automobile

Possible fine printing in the normal mask thickness

AMP

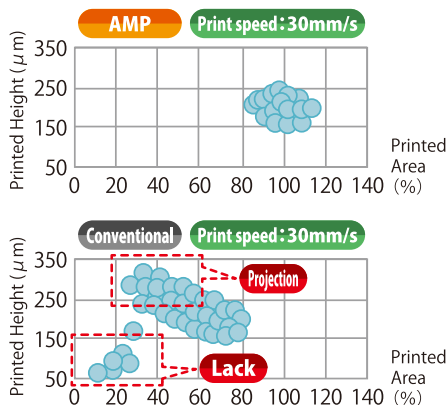
Newly developed synthetic resin with enhanced water resistance



- Friction reduction between stencil mask ▶ Fine-pitch pattern printability
- Water-resistant property ▶ Electric reliability improvement

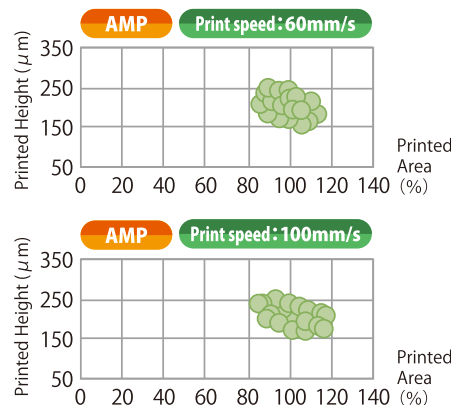
Stable Printability for Fine-pitch Pattern

Fine-pitch Printability



Application of the new development resin ▶
Realize superior printability for Fine-pitch pattern

Wettability at Lead Edge



Possible stable printing ▶
Shortening of the production time

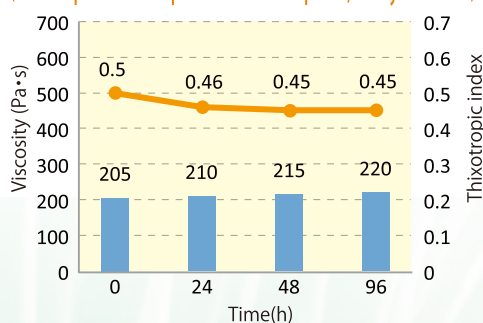
Test condition

- Opening size : 275 μmΦ
- Print thickness : 150 μm

Superior viscosity stability

Viscosity and Thixotropy change

<80% of paste was replaced with new paste, every 12 hours>



0.4mm QFP



Conventional

AMP

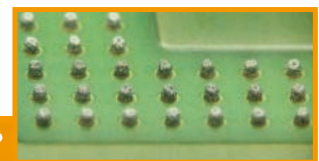


0.5mm BGA



Conventional

AMP



Capable soldering at 0.4mm QFP & 0.5mm BGA
with 150 μm thickness stencil mask